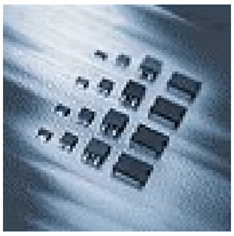

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC030P03NS3 G	**Issued**	4. August 2015
MA#	MA001403694		
Package	PG-TDSON-8-1	**Weight***	122.81 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.418	4.41	4.41	44113	44113
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		308	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		92	
	non noble metal	copper	7440-50-8	37.762	30.75	30.79	307476	307876
wire	non noble metal	copper	7440-50-8	0.023	0.02	0.02	185	185
encapsulation	organic material	carbon black	1333-86-4	0.078	0.06		634	
	plastics	epoxy resin	-	5.528	4.50		45013	
	inorganic material	silicondioxide	60676-86-0	33.324	27.13	31.69	271344	316991
leadfinish	non noble metal	tin	7440-31-5	1.470	1.20	1.20	11968	11968
plating	noble metal	silver	7440-22-4	0.166	0.13	0.13	1348	1348
solder	noble metal	silver	7440-22-4	0.101	0.08		824	
	non noble metal	tin	7440-31-5	0.081	0.07		660	
	non noble metal	lead	7439-92-1	3.868	3.15	3.30	31495	32979
CLIP plating	noble metal	silver	7440-22-4	1.289	1.05	1.05	10499	10499
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		92	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	copper	7440-50-8	11.320	9.22	9.23	92174	92294
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		182	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	copper	7440-50-8	22.292	18.15	18.18	181510	181747
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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